

CD4504BMS

CMOS Hex Voltage Level Shifter for TTL-to-CMOS or CMOS-to-CMOS Operation

December 1992

Features

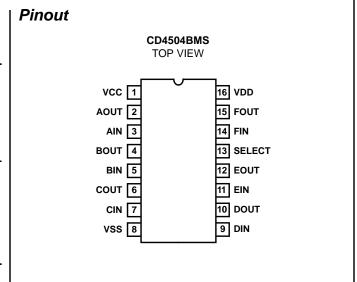
- · High Voltage Type (20V Rating)
- Independence of Power Supply Sequence Considerations
 - VCC can Exceed VDD
 - Input Signals can Exceed Both VCC and VDD
- . Up and Down Level Shifting Capability
- Shiftable Input Threshold for Either CMOS or TTL Compatibility
- 100% Tested for Quiescent Current at 20V
- 5V. 10V and 15V Parametric Ratings
- Standardized Symmetrical Output Characteristics
- Maximum Input Current of 1µA at 18V Over Full Package Temperature Range; 100nA at 18V and +25°C
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Description

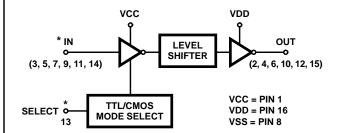
CD4504BMS hex voltage level shifter consists of six circuits which shift input signals from the VCC logic level to the VDD logic level. To shift TTL signals to CMOS logic levels, the SELECT input is at the VCC HIGH logic state. When the SELECT input is at a LOW logic state, each circuit translates signals from one CMOS level to another.

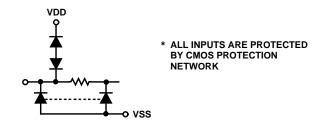
The CD4504BMS is supplied in these 16-lead outline packages:

H1F Frit Seal DIP Ceramic Flatpack H6W



Functional Diagram





Reliability Information Absolute Maximum Ratings Ceramic DIP and FRIT Package θ_{ja} Flatnack Package 80°C/W DC Supply Voltage Range, (VDD) -0.5V to +20V Thermal Resistance $_{20^{o}\text{C/W}}^{\theta_{jc}}$ (Voltage Referenced to VSS Terminals) Flatpack Package 70°C/W Input Voltage Range, All Inputs -0.5V to VDD +0.5V 20°C/W Maximum Package Power Dissipation (PD) at +125°C DC Input Current, Any One Input±10mA Operating Temperature Range.....-55°C to +125°C For TA = -55° C to $+100^{\circ}$ C (Package Type D, F, K).....500mW Package Types D, F, K, H For TA = $+100^{\circ}$ C to $+125^{\circ}$ C (Package Type D, F, K) Derate Storage Temperature Range (TSTG) -65°C to +150°C Linearity at 12mW/°C to 200mW Lead Temperature (During Soldering) +265°C Device Dissipation per Output Transistor 100mW At Distance 1/16 \pm 1/32 Inch (1.59mm \pm 0.79mm) from case for For TA = Full Package Temperature Range (All Package Types) 10s Maximum

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

				GROUP A		LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS (I	NOTE 1)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VD	D or GND	1	+25°C	-	2	μΑ
				2	+125°C	-	200	μΑ
		VDD = 18V, VIN = VD	D or GND	3	-55°C	-	2	μΑ
Input Leakage Current	IIL	VIN = VDD or GND	VDD = 20	1	+25°C	-100	-	nA
				2	+125°C	-1000	-	nA
			VDD = 18V	3	-55°C	-100	-	nA
Input Leakage Current	IIH	VIN = VDD or GND	VDD = 20	1	+25°C	-	100	nA
				2	+125°C	-	1000	nA
			VDD = 18V	3	-55°C	-	100	nA
Output Voltage	VOL15	VDD = 15V, No Load	•	1, 2, 3	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH15	VDD = 15V, No Load	(Note 3)	1, 2, 3	+25°C, +125°C, -55°C	14.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.	.4V	1	+25°C	0.53	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0	0.5V	1	+25°C	1.4	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT =	1.5V	1	+25°C	3.5	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.	.6V	1	+25°C	-	-0.53	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.	.5V	1	+25°C	-	-1.8	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9	9.5V	1	+25°C	-	-1.4	mA
Output Current (Source)	IOH15	VDD = 15V, VOUT =	13.5V	1	+25°C	-	-3.5	mA
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10	μΑ	1	+25°C	-2.8	-0.7	V
P Threshold Voltage	VPTH	VSS = 0V, IDD = 10μ/	4	1	+25°C	0.7	2.8	V
Functional	F	VDD = 4.5V, VCC = 2 VIN = VDD or GND	.8,	7	+25°C	VOH > VDD/2	VOL < VDD/2	V
		VDD = 4.5V, VCC = 3 VIN = VDD or GND	.0,	8B	-55°C			
		VDD = 18V, VCC = 18 VIN = GND or VCC	BV,	8A	+125°C			
		VDD = 18V, VCC = 4. VIN = VCC or GND	5V,	8A	+125°C			
		VDD = 4.5V, VCC = 1 VIN = VCC or GND	8V,	8A	+125°C			
		VDD = 20V, VCC = 20 VIN = GND or VCC)V,	7	+25°C			
		VDD = 20V, VCC = 4. VIN = VCC or GND	5V,	7	+25°C			
		VDD = 4.5V, VCC = 2 VIN = VCC or GND	0V,	7	+25°C			

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

			GROUP A		LIM	ITS	
PARAMETER	SYMBOL	CONDITIONS (NOTE 1)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Input Voltage Low (Note 2) TTL-CMOS	VIL	VDD = 15V, VOH > 13.5V, VOL < 1V VCC = 5V	1, 2, 3	+25°C, +125°C, -55°C	-	0.8	V
Input Voltage High (Note 2) TTL-CMOS	VIH	VDD = 15V, VOH > 13.5V, VOL < 1V VCC = 5V	1, 2, 3	+25°C, +125°C, -55°C	2	-	V
Input Voltage Low (Note 2) CMOS-CMOS	VIL	VDD = 10V, VOH > 9V, VOL < 1V VCC = 5V	1, 2, 3	+25°C, +125°C, -55°C	-	1.5	V
Input Voltage High (Note 2)CMOS-CMOS	VIH	VDD = 10V, VOH > 9V, VOL < 1V VCC = 5V	1, 2, 3	+25°C, +125°C, -55°C	3.5	-	V
Input Voltage Low (Note 2) CMOS-CMOS	VIL	VDD = 15V, VOH > 13.5V, VOL < 1.5V, VCC = 10V	1, 2, 3	+25°C, +125°C, -55°C	-	3	V
Input Voltage High (Note 2) CMOS-CMOS	VIH	VDD = 15V, VOH > 13.5V, VOL < 1.5V, VCC = 10V	1, 2, 3	+25°C, +125°C, -55°C	7		V

NOTES: 1. All voltages referenced to device GND, 100% testing being 3. For accuracy, voltage is measured differentially to VDD. Limit implemented. is 0.050V max.

2. Go/No Go test with limits applied to inputs.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

			GROUP A		LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS (NOTE 1, 2)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPHL1	VDD = 10V, VIN = VCC or GND	9	+25°C	-	280	ns
TTL to CMOS VDD > VCC		VCC = 5V	10, 11	+125°C, -55°C	-	378	ns
Propagation Delay	TPHL2	VDD = 10V, VIN = VCC or GND	9	+25°C	-	240	ns
CMOS to CMOS VDD > VCC		VCC = 5V	10, 11	+125°C, -55°C	-	324	ns
Propagation Delay	TPHL3	VDD = 5V, VIN = VCC or GND	9	+25°C	-	550	ns
CMOS to CMOS VCC > VDD		VCC = 10V	10, 11	+125°C, -55°C	-	743	ns
Propagation Delay	TPLH1	VDD = 10V, VIN = VCC or GND	9	+25°C	-	280	ns
TTL to CMOS VDD > VCC		VCC = 5V	10, 11	+125°C, -55°C	-	378	ns
Propagation Delay	TPLH2	VDD = 10V, VIN = VCC or GND	9	+25°C	-	240	ns
CMOS to CMOS VDD > VCC		VCC = 5V	10, 11	+125°C, -55°C	-	324	ns
Propagation Delay	TPLH3	VDD = 5V, VIN = VCC or GND	9	+25°C	-	400	ns
CMOS to CMOS VCC > VDD		VCC = 10V	10, 11	+125°C, -55°C	-	540	ns
Transition Time	TTHL	All Modes	9	+25°C	-	200	ns
	TTLH		10, 11	+125°C, -55°C	·	270	ns

NOTES:

- 1. CL = 50pF, RL = 200K, Input TR, TF < 20ns.
- 2. -55°C and +125°C limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIN		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 5V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	1	μА
				+125°C	-	30	μА
		VDD = 10V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	2	μА
				+125°C	-	60	μА
		VDD = 15V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	2	μА
				+125°C	-	120	μΑ
Output Voltage	VOL	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOL	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	4.95	-	V
Output Voltage	VOH	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	9.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V	1, 2	+125°C	0.36	-	mA
				-55°C	0.64	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V	1, 2	+125°C	0.9	-	mA
				-55°C	1.6	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V	1, 2	+125°C	2.4	-	mA
				-55°C	4.2	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V	1, 2	+125°C	-	-0.36	mA
				-55°C	-	-0.64	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V	1, 2	+125°C	-	-1.15	mA
				-55°C	-	-2.0	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V	1, 2	+125°C	-	-0.9	mA
				-55°C	-	-1.6	mA
Output Current (Source)	IOH15	VDD =15V, VOUT = 13.5V	1, 2	+125°C	-	-2.4	mA
				-55°C	-	-4.2	mA
Input Voltage Low TTL - CMOS	VIL	VDD = 10V, VOH > 9V, VOL < 1V, VCC = 5V	1, 2	+25°C, +125°C, -55°C	=	0.8	V
Input Voltage High TTL - CMOS	VIH	VDD = 10V, VOH > 9V, VOL < 1V, VCC = 5V	1, 2	+25°C, +125°C, -55°C	2	-	V
Input Voltage Low CMOS - CMOS	VIL	VDD = 15V, VOH > 13.5V, VOL < 1.5V, VCC = 5V	1, 2	+25°C, +125°C, -55°C	-	1.5	V
Input Voltage High CMOS - CMOS	VIH	VDD = 15V, VOH > 13.5V, VOL < 1.5V, VCC = 5V	1, 2	+25°C, +125°C, -55°C	3.5	-	V
Propagation Delay TTL - CMOS, VDD > VCC	TPHL1	VDD = 15V, VCC = 5V	1, 2, 3	+25°C	-	280	ns
Propagation Delay	TPHL2	VDD = 15V, VCC = 5V	1, 2, 3	+25°C	-	240	ns
CMOS - CMOS, VDD > VCC		VDD = 15V, VCC = 10V	1, 2, 3	+25°C	-	140	ns
Propagation Delay	TPHL3	VDD = 5V, VCC = 15V	1, 2, 3	+25°C	-	550	ns
CMOS - CMOS, VCC > VDD		VDD = 10V, VCC = 15V	1, 2, 3	+25°C	-	140	ns
Propagation Delay TTL - CMOS, VDD > VCC	TPLH1	VDD = 15V, VCC = 5V	1, 2, 3	+25°C	-	280	ns

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

					LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPLH2	VDD = 15V, VCC = 5V	1, 2, 3	+25°C	-	240	ns
CMOS - CMOS, VDD > VCC		VDD = 15V, VCC = 10V	1, 2, 3	+25°C	-	140	ns
Propagation Delay	TPLH3	VDD = 5V, VCC = 15V	1, 2, 3	+25°C	-	400	ns
CMOS - CMOS VCC > VDD		VDD = 10V, VCC = 15V	1, 2, 3	+25°C	-	120	ns
Transition Time	TTHL	VDD = 10V	1, 2, 3	+25°C	-	100	ns
	TTLH	VDD = 15V	1, 2, 3	+25°C	-	80	ns
Input Capacitance	CIN	Any Input	1, 2	+25°C	-	7.5	pF

NOTES:

- 1. All voltages referenced to device GND.
- 2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
- 3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VDD or GND	1, 4	+25°C	-	7.5	μΑ
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10μA	1, 4	+25°C	-2.8	-0.2	V
N Threshold Voltage Delta	ΔVTN	VDD = 10V, ISS = -10μA	1, 4	+25°C	-	±1	V
P Threshold Voltage	VTP	VSS = 0V, IDD = 10μA	1, 4	+25°C	0.2	2.8	V
P Threshold Voltage Delta	ΔVΤΡ	VSS = 0V, IDD = 10μA	1, 4	+25°C	-	±1	V
Functional	F	VDD = 18V, VIN = VDD or GND	1	+25°C	VOH >	VOL <	V
		VDD = 3V, VIN = VDD or GND			VDD/2	VDD/2	
Propagation Delay Time	TPHL TPLH	VDD = 5V	1, 2, 3, 4	+25°C	-	1.35 x +25°C Limit	ns

NOTES: 1. All voltages referenced to device GND.

3. See Table 2 for +25°C limit.

2. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

4. Read and Record

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

PARAMETER	SYMBOL	DELTA LIMIT
Supply Current - MSI-1	IDD	± 0.2μA
Output Current (Sink)	IOL5	± 20% x Pre-Test Reading
Output Current (Source)	IOH5A	± 20% x Pre-Test Reading

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUP	MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Pre Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 1 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 2 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)	100% 5004	1, 7, 9, Deltas	

TABLE 6. APPLICABLE SUBGROUPS (Continued)

CONFORMANCE GROUP		MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Interim Test	3 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note	e 1)	100% 5004	1, 7, 9, Deltas	
Final Test		100% 5004	2, 3, 8A, 8B, 10, 11	
Group A		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B	Subgroup B-5	Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
Subgroup B-6		Sample 5005	1, 7, 9	
Group D		Sample 5005	1, 2, 3, 8A, 8B, 9	Subgroups 1, 2 3

NOTE: 1.5% Parameteric, 3% Functional; Cumulative for Static 1 and 2.

TABLE 7. TOTAL DOSE IRRADIATION

	MIL-STD-883	TEST READ AND RECOR		RECORD	
CONFORMANCE GROUPS	METHOD	PRE-IRRAD	POST-IRRAD	PRE-IRRAD	POST-IRRAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS

			OSCILL		LATOR	
FUNCTION	OPEN	GROUND	VDD	9V \pm -0.5V	50kHz	25kHz
Static Burn-In 1 (Note 1)	2, 4, 6, 10, 12, 15	3, 5, 7-9, 11, 14	16	1, 13		
Static Burn-In 2 (Note 1)	2, 4, 6, 10, 12, 15	8	16	1, 3, 5, 7, 9, 11, 13, 14		
Dynamic Burn- In (Note 1, 3)	-	8	16	1, 2, 4, 6, 10, 12, 15	3, 5, 7, 9, 11, 14	
Irradiation (Note 2)	2, 4, 6, 10, 12, 15	8	1, 3, 5, 7, 9, 11, 13, 14, 16			

NOTES:

- 1. Each pin except VCC, VDD and GND will have a series resistor of 10K \pm 5%, VDD = 18V \pm 0.5V
- 2. Each pin except VCC, VDD and GND will have a series resistor of 47K \pm 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = $10V \pm 0.5V$
- 3. Oscillator output to be VDD/2.

Typical Performance Characteristics

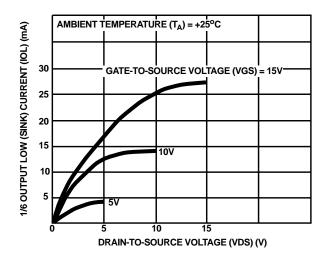


FIGURE 1. TYPICAL OUTPUT LOW (SINK) CURRENT

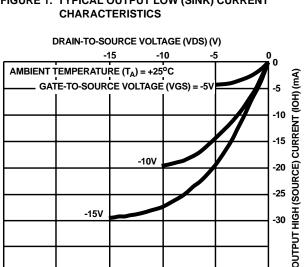


FIGURE 3. TYPICAL OUTPUT HIGH (SOURCE) CURRENT **CHARACTERISTICS**

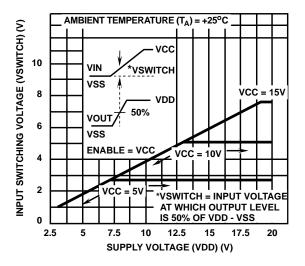


FIGURE 5. TYPICAL INPUT SWITCHING AS A FUNCTION OF HIGH LEVEL SUPPLY VOLTAGE (SELECT AT VCC-CMOS MODE)

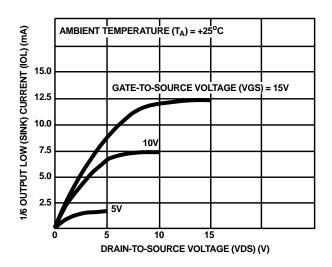


FIGURE 2. MINIMUM OUTPUT LOW (SINK) CURRENT **CHARACTERISTICS**

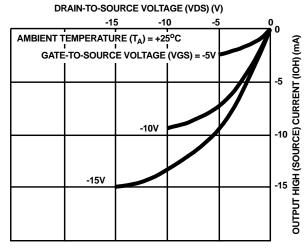


FIGURE 4. MINIMUM OUTPUT HIGH (SOURCE) CURRENT **CHARACTERISTICS**

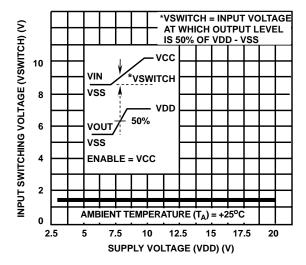


FIGURE 6. TYPICAL INPUT SWITCHING AS A FUNCTION OF HIGH LEVEL SUPPLY VOLTAGE (SELECT AT **VSS-TTL MODE)**

Typical Performance Characteristics (Continued)

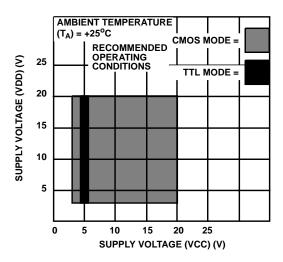
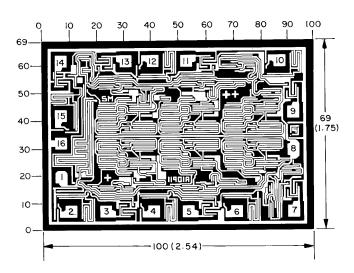


FIGURE 7. HIGH LEVEL SUPPLY VOLTAGE vs LOW LEVEL SUPPLY VOLTAGE

Chip Dimensions and Pad Layout



Dimensions in parenthesis are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch) .

METALLIZATION: Thickness: 11kÅ – 14kÅ, AL.

PASSIVATION: 10.4kÅ - 15.6kÅ, Silane

BOND PADS: 0.004 inches X 0.004 inches MIN **DIE THICKNESS:** 0.0198 inches - 0.0218 inches

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